



Vectron's VC-840 Crystal Oscillator (XO) is a quartz stabilized square wave generator with a CMOS output. The VC-840 is a fundamental oscillator resulting in very low jitter performance, and a monolithic IC which improves reliability and reduces cost.

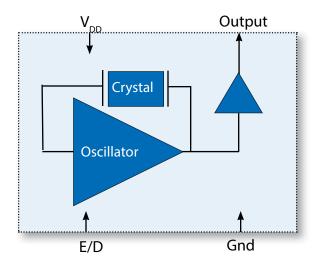
Features

- CMOS output XO
- 1-60.0000 MHz Output Frequency
- 1.8, 2.5 or 3.3 V Operation
- Fundamental Crystal Design with low Jitter Performance
- Output Disable Feature
- Small Industry Standard Package, 2.5x2.0x0.9mm
- Product is compliant to RoHS directive and fully compatible with lead free assembly

Applications

- SONET/SDH/DWDM
- Ethernet, GE, SynchE
- Storage Area Networking
- Fiber Channel
- Digital Video
- Broadband Access
- Base Stations, Picocells

Block Diagram



Specifications

Table 1. Electrical Performance					
Parameter	Symbol	Min	Typical	Maximum	Units
		Supply			
Voltage ¹	$V_{_{DD}}$		3.3		V
Maximum Voltage		-0.5		7	V
Current ² , <20.000MHz 20.000-40.000MHz 40.001-60.000MHz 60.001-75.000Mhz	I _{DD}			7 13 19 24	mA
Current, Output Disabled				10	uA
		Frequency			
Nominal Frequency	f_N	0.75		60	MHz
Stability ³ , Ordering Information		±	£25, ±50 or ±10	ppm	
		Outputs			
Output Logic Levels ² Output Logic High Output Logic Low Output Logic High Drive Output Logic Low Drive	V _{OH} V _{OL} I _{OH} I _{OL}	0.9*V _{DD} 4 4		0.1*V _{DD}	V V mA mA
Load	I _{OUT}			15	pF
Output Rise /Fall Time²	t _R /t _F		2.5	5	ns
Duty Cycle ² , ⁴		45		55	%
Period Jitter ^s RMS Peak-Peak	фЛ		1.5 12		ps
	Ena	ble/Disable			
Output Enable/Disable ⁶ Output Enable Output Disable	V _{IH} V _{IL}	0.7*VDD		0.3*VDD	V V
Disable Time				150	ns
Start-Up Time	t _{su}			10	ms
Operating Temp, Ordering Information	T_{OP}		-20/70 or -40/85	5	°C

- 1] The power supply should have by-pass capacitors as close to the supply and to ground as possible, for example 0.1 and 0.01uF.
- 2] Parameters are tested with production test circuit below , Figure 1.
- 3] Includes initial accuracy, operating temperature, supply voltage, shock and vibration (not under operation) and aging
- 4] Duty Cycle is measured as On Time/Period (Fig 2).
- 5] Broadband Period Jitter measured using LeCroy Waverunner 610Zi, 200k minimum samples
- 6] The Output is Enabled if the Enable/Disable is left open.

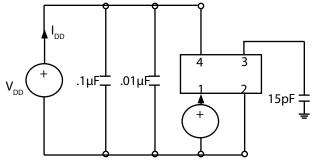




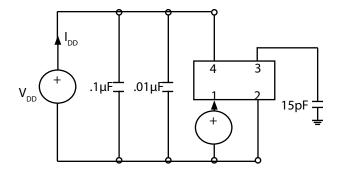
Fig 1: Test Circuit Fig 2: Waveform

V_{он} 50%

Specifications

Parameter	Symbol	Min	Typical	Maximum	Units
	<u> </u>	Supply			
Voltage ¹	V _{DD}		2.5		V
Maximum Voltage	<i>55</i>	-0.5		7	V
Current ² , <20.000MHz 20.000-40.000MHz 40.001-60.000MHz 60.001-75.000Mhz	I _{DD}			5 9 11 14	mA
Current, Output Disabled				10	uA
		Frequency			
Nominal Frequency	f_N	0.75		60	MHz
Stability ³ , Ordering Information		=	±25, ±50 or ±10	0	ppm
		Outputs			
Output Logic Levels ² Output Logic High Output Logic Low Output Logic High Drive Output Logic Low Drive	V _{ОН} V _{OL} I _{ОН} I _{OL}	0.9*V _{DD} 4 4		0.1*V _{DD}	V V mA mA
Load	I _{OUT}			15	pF
Output Rise /Fall Time²	t _R /t _F		2.5	5	ns
Duty Cycle ² , ⁴		40		60	%
Period Jitter ⁵ RMS Peak-Peak	фЛ		1.5 12		ps
	Ena	able/Disable			
Output Enable/Disable ⁶ Output Enable Output Disable	V _{IH} V _{IL}	0.7*VDD		0.3*VDD	V V
Disable Time				150	ns
Start-Up Time	t _{su}			10	ms
Operating Temp, Ordering Information	T_{OP}		-20/70 or -40/85	5	°C

- 1] The power supply should have by-pass capacitors as close to the supply and to ground as possible, for example 0.1 and 0.01uF.
- 2] Parameters are tested with production test circuit below , Figure 1.
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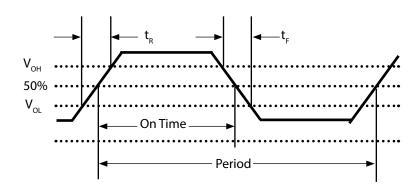


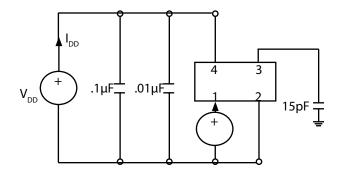
Fig 3: Test Circuit

Fig 4: Waveform

Specifications

Parameter	Symbol	Min	Typical	Maximum	Units
	-,	Supply	7) 1		
Voltage ¹	V _{DD}		1.8		V
Maximum Voltage	<u>UU</u>	-0.5		7	V
Current ² , <20.000MHz 20.000-40.000MHz 40.001-50.000MHz	l _{DD}			2.5 3.0 3.5	mA
Current, Output Disabled				10	uA
		Frequency			
Nominal Frequency	f_N	0.75		60	MHz
Stability ³ , Ordering Information		±	±25, ±50 or ±10	0	ppm
		Outputs			
Output Logic Levels ² Output Logic High Output Logic Low Output Logic High Drive Output Logic Low Drive	V _{OH} V _{OL} I _{OH} I _{OL}	0.9*V _{DD} 4 4		0.1*V _{DD}	V V mA mA
Load	I _{OUT}			15	pF
Output Rise /Fall Time ²	t _R /t _F		2.5	5	ns
Duty Cycle ² , ⁴		45		55	%
Period Jitter ⁵ RMS Peak-Peak	фЈ		1.5 12		ps
	Ena	able/Disable			
Output Enable/Disable ⁶ Output Enable Output Disable	V _{IH} V _{IL}	0.7*VDD		0.3*VDD	V V
Disable Time				150	ns
Start-Up Time	t _{su}			10	ms
Operating Temp, Ordering Information	T _{OP}		-20/70 or -40/8	5	°C

- 1] The power supply should have by-pass capacitors as close to the supply and to ground as possible, for example 0.1 and 0.01uF.
- 2] Parameters are tested with production test circuit below, Figure 1.
- 3] Includes initial accuracy, operating temperature, supply voltage, shock and vibration (not under operation) and aging
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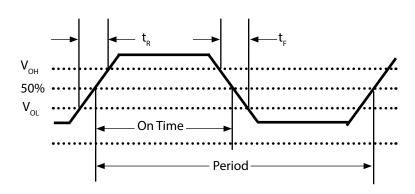
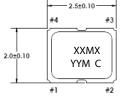
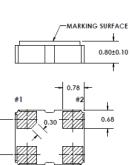


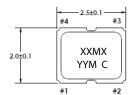
Fig 5: Test Circuit Fig 6: Waveform

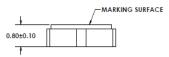
Outline Drawing & Pad Layout

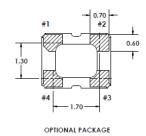


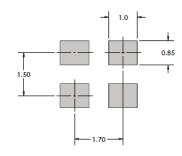


PRIMARY PACKAGE









Dimensions in mm

Table 4	Table 4. Pin Out									
Pin	n Symbol Function									
1	E/D	Enable Disable								
2	GND	Case and Electrical Ground								
3	Output	Output								
4	$V_{_{ m DD}}$	Power Supply Voltage								

VI qualification includes aging at various extreme temperatures, shock and vibration, temperature cycling, and IR reflow simulation. The VC-840 family is capable of meeting the following qualification tests:

Table 5. Environmental Compliance										
Parameter	Conditions									
Mechanical Shock	MIL-STD-883, Method 2002									
Mechanical Vibration	MIL-STD-883, Method 2007									
Solderability	MIL-STD-883, Method 2003									
Gross and Fine Leak	MIL-STD-883, Method 1014									
Resistance to Solvents	MIL-STD-883, Method 2015									
Moisture Sensitivity Level	MSL 1									
Contact Pads	Gold over Nickel									

Although ESD protection circuitry has been designed into the VC-840 proper precautions should be taken when handling and mounting. VI employs a human body model (HBM) and a charged device model (CDM) for ESD susceptibility testing and design protection evaluation.

Table 6. ESD Ratings										
Model	Model Minimum Cond									
Human Body Model	1500V	MIL-STD-883, Method 3015								
Charged Device Model	1000V	JESD22-C101								

Stresses in excess of the absolute maximum ratings can permanently damage the device. Functional operation is not implied at these or any other conditions in excess of conditions represented in the operational sections of this datasheet. Exposure to absolute maximum ratings for extended periods may adversely affect device reliability. Permanent damage is also possible if E/D is applied before V_{DD} .

Table 7. Absolute Maximum Ratings										
Parameter	Symbol	Ratings	Unit							
Storage Temperature	T _s	-55 to 100	°C							
Soldering Temp/Time	T _{LS}	260 / 10	°C / sec							

IR Reflow

Solderprofile:

The VC-840 is qualified to meet the JEDEC standard for Pb-Free assembly. The temperatures and time intervals listed are based on the Pb-Free small body requirements. The VC-840 device is hermetically sealed so an aqueous wash is not an issue.

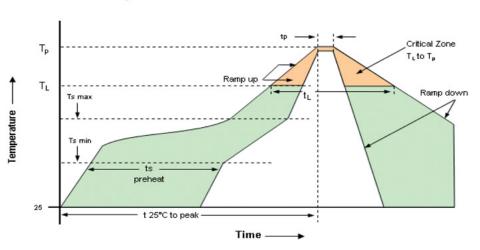
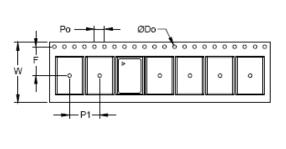
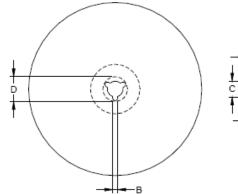


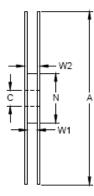
Table 8. Reflow Profile										
Parameter	Symbol	Value								
PreHeat Time Ts-min Ts-max	t _s	60 sec Min, 260 sec Max 150°C 200°C								
Ramp Up	R _{UP}	3 °C/sec Max								
Time Above 217 °C	t _L	60 sec Min, 150 sec Max								
Time To Peak Temperature	T _{AMB-P}	480 sec Max								
Time at 260 °C	t _p	30 sec Max								
Ramp Down	R _{DN}	6 °C/sec Max								

Tape and Reel

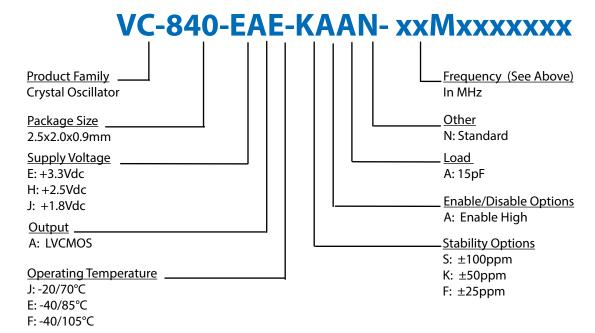
Table 9 . Tape	and Re	el Dimer	sions										
Tape Dimensions (mm)					Reel Dimensions (mm)								
Dimension	W	F	Do	Po	P1	Α	В	С	D	N	W1	W2	# Per
Tolerance	Тур	Тур	Тур	Тур	Тур	Тур	Min	Тур	Min	Min	Тур	Max	Reel
VC-840	8.0	3.5	1.5	4.0	4.0	180							1000
													2000







Ordering Information



Example: VC-840-EAE-KANN-25M0000000 = 2.5x2.0, +3.3V, LVCMOS output, ± 50 ppm over -40/85°C with a 25.000MHz output

 $Note: Not all \ combinations \ of \ options \ are \ available. \ Other \ specifications \ may \ be \ available \ upon \ request. \ Consult \ with \ factory.$

* Add **_SNPBDIP** for tin lead solder dip Example: VC-840-EAE-KANN-25M0000000 SNPBDIP

Revision History Approved Revision Date Edited Description May 14, 2014 VN TG Corrected Operating Temperature in Specification Tables 1, 2 and 3 to show -20/70C. Removed Standard Output Frequencies Table 10 (Empty) Added temp range -40/105°C and note in RED on page 7 Aug 4, 2015 ΕM DL Aug 16, 2015 DL Updated Rise/Fall time. ΕM Jan 17, 2017 RC RC Update IR Reflow Table FΒ FΒ Update logo and contact information, added SNPBDIP ordering option Aug 10, 2018



Microsemi Headquarters

One Enterprise, Aliso Viejo, CA 92656 USA
Within the USA: +1 (800) 713-4113
Outside the USA: +1 (949) 380-6100
Sales: +1 (949) 380-6136
Fax: +1 (949) 215-4996
email: sales.support@microsemi.com
www.microsemi.com

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